Prosperity Dielectrics Co., Ltd.

No.566-1, Kaoshi Rd., Yangmei, Taoyuan 32668, Taiwan (R.O.C.) Tel: 886-3-4753355 Fax: 886-3-4854959

Messrs.	:	一般共用
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Date: 2020/02/11

APPROVAL SHEET

Product Name: Stacked Capacitors

Part No.: FE Series

Description: Size 1210~2225, C0G/X7R, 50~630Vdc

PREPARED BY	APPROVED BY
146011	

信昌電子陶瓷股份有限公司

PROSPERITY DIELECTRICS CO., LTD.

桃園市楊梅區高獅路 566-1 號 http://www.pdc.com.tw

Tel: 03-4753355 ext: Fax: 03-4854959

Contactor: ____ Mobile: ____

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SPECIFICATION

FOR

Product Name: Stacked Capacitors

Part No.: FE Series

Description: Size 1210~2225, C0G/X7R, 50~630Vdc

SPEC. No.: FE-000-001-09

DATE: 2020/02/11

DRAWN BY	CHECEKED BY	APPROVED BY		
Jane Hsiao	Yvens Chou	Joseph Ling		

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1. INTRODUCTION

FE Series green type capacitors are manufactured by using green materials without lead and cadmium. These capacitors to achieve a unique structure of high reliability. The use of metal lead frame, can absorb the heat and mechanical stress. ESR (equivalent series resistance), ESL (equivalent series inductance) is small, the most suitable for high frequency operation of the rectifier power supply.

2. FEATURES

Table 1

Code

- a. High reliability and stability.
- b. Higher mechanical endurance.
- c. Anti thermal stress and mechanical stress.
- d. Improved vibration performance.
- e. More capacitance without changing footprint.
- f. RoHS & HALOGEN Compliant.

3. APPLICATIONS

- a. DC to DC converter.
- b. High voltage coupling/DC blocking.
- c. Back-lighting inverters.
- d. Snubbers in high frequency power converters.
- e. Power supplies.
- f. Surge protection.
- g. Filtering, smoothing, and decoupling application.

4. HOW TO ORDER

<u>FE</u>	<u>2H</u>	<u>X</u>	<u>106</u>	<u>K</u>	<u>500</u>	<u>L</u>	<u>G</u>	<u>K</u>	<u>M</u>
PDC Family	Size	Dielectric	Capacitance	Tolerance	Rated Voltage	Packaging	Thickness	Control Code	Special Code
Table 1	Table 2	Table 3	Table 4	Table 5	Table 6	Table 7	Table 8	Table 9	Table 10

FE			St	tacked Ca	pacitors	Series	PASSIVE S
					Z	17	
Table	Table 2 Stack chip quantity and chip size						
The firs	t dig	it:#ofch	nips in s	tack	1	0	0
Second	digi	t code : c	hip size	(below)	,	100	MAL
						UL	

PDC Family

Table	6		Ra	ated Voltage)	
Code		Description	Code	Description	Code	Description
м 500 та	SC.	50Vdc	251	250Vdc		
101		100Vdc	501	500Vdc		
201	Ž,	200Vdc	631	630Vdc		

Tab	le 2	Stack chip quantity and chip size					
The first digit : # of chips in stack							
Second digit code : chip size (below)							
Code	Des	scription	Code	Description	Code	Description	
Α	1210	(3225)	G	1825 (4563)	I	2225 (5763)	
С	1812	2 (4532)	Н	2220 (5750)		LLL	

Table	7 Pack	Packaging Type					
Code	Description	Code	Description				
(B).\	Bulk	Т	Tray package				
L	Tape and 13" Reel, Embossed Tape						

Table 3 Dielectric Material Characteristics					
Code	Description		Code	Description	
N	COG		Х	X7R	

Table	ole 4 Capacitance Rule Code				
Code	Description		Code	Description	
R47	0.47pF		102	102=10x10 ² =1000pF	
0R5	0.5pF		104	104=10x10 ⁴ =100nF	
100	100=10x10 ⁰ =10pF		106	106=10x10 ⁶ =10μF	

T	able 8	Thickness Description				
Code	Description	Code	Description	Code	Description	
Α	3.00±0.35 mm	J	7.80±0.35 mm	S	12.60±0.35 mm	
В	3.60±0.35 mm	K	8.40±0.35 mm	Т	13.20±0.35 mm	
С	4.20±0.35 mm	L	9.00±0.35 mm	U	1.70±0.25 mm	
D	4.80±0.35 mm	М	9.60±0.35 mm	٧	2.10±0.25 mm	
Е	5.40±0.35 mm	N	10.20±0.35 mm	W	2.50±0.25 mm	
F	6.00±0.35 mm	Р	10.80±0.35 mm			
G	6.60±0.35 mm	Q	11.40±0.35 mm			
Н	7.20±0.35 mm	R	12.00±0.35 mm			

Table	e 5	Tolerance				
Code	Description	Code	Description	Code	Description	
Α	±0.05 pF	-	-10% ~ 0%	Q	±0.03 pF	
В	±0.10 pF	J	±5 %	Z	-20% ~ +80%	
С	±0.25 pF	K	±10 %	Х	+10% ~ +20%	
D	±0.50 pF	L	0% ~ +10%			
F	±1 %	М	±20 %			
G	±2 %	N	-5% ~ +10%			
Н	±3 %	Р	±0.02 pF			

Table 9	Control Code						
Code	Description	Code	Description				
L	L type lea	K	K type lead				
J	J type lead	В	B type lead				
S	Straight type lead	F	Straight type lead				

Table 10	Special Code				
Blank		М	Automotive		

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5. EXTERNAL DIMENSIONS

Size Inch (mm)	L (mm)	W (mm)	Code / T (mm)	E (mm)	
1210 (3225)	3.50±0.40	2.50±0.40		1.70±0.15	L Type Lead
1812 (4532)	4.80±0.40	3.20±0.40		1.70±0.15	₩, /*
1825 (4563)	4.80±0.40	6.30±0.50	Reference Table 8	1.70±0.15	T
2220 (5750)	6.00±0.50	5.00±0.50		1.70±0.15	J Type Lead E →
2225 (5763)	6.00±0.50	6.30±0.50		1.70±0.15	Fig. 5.1 The outline of Stacked Capacitors

6. GENERAL ELECTRICAL DATA

Dielectric	COG 所有 信息	X7R			
Size	1210, 1812, 1825, 2220, 2225	1210, 1812, 1825, 2220, 2225			
Rated voltage (WVDC)	50V, 100V, 200V, 250V, 500V, 630V	50V, 100V, 200V, 250V, 500V, 630V			
Capacitance range	220nF Max.	47μF Max.			
Capacitance tolerance	Reference to Table 5 YSTEM ALLIANCE	Reference to Table 5			
Tan δ	Cap. Range Q Spec. Cap. Q≥400+20C Cap.≥30pF Q≥1000	Cap. Range D.F. Spec. 1210≥3.3μF ≤5.0% 1812~2225≥10μF ≤5.0%			
	Dielecti	Other ≤2.5%			
	Measured at the condition of 30~70% related humidity	Measured at the condition of 30~70% related humidity			
Capacitance & Tan δ	For 25°C at ambient temperature	Preconditioning for Class II MLCC: Perform a heat treatment at 150±10°C for 1 hour, then leave in ambien condition (25°C) for 24±2 hours before measurement			
Test condition	Cap. Range Test Condition Cap.<1000pF 1.0±0.2Vrms, 1.0MHz±10% Cap.≥1000pF 1.0±0.2Vrms, 1.0KHz±10%	Cap. Range Test Condition Cap.≤10μF 1.0±0.2Vrms, 1.0KHz±10% Cap.>10μpF 0.5±0.2Vrms, 120Hz±20%			
Insulation resistance at Ur	≥10GΩ or RxC≥500Ω-F, whichever is smaller	≥10GΩ or RxC≥100Ω-F, whichever is smaller			
Operating temperature	-55 to +125°C	-55 to +125°C			
Capacitance characteristic	±30ppm/°C	±15%			
Termination	L / J / Straight type lead	L / J / Straight type lead			

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7. CAPACITANCE RANGE (Max.)

7-1. C0G

Dimension	Code	Rated Voltage					
Dimension	Code	50V	100V	200V	250V	500V	630V
1210	1A	393	223	103	103	103	103
1812	1C	104	473	273	273	223	223
1012	2C	224(M)	104	563	563	473(M)	473(M)
1825	1G	104	104	683	683	473	223
1025	2G	224(M)	224(M)	134	134	104	473(M)
2220	1H	104	104	683	683	473	223
2220	2H	224(M)	224(M)	134	134	104	473(M)
2225	11	104	104	104	104	823	683
2225	21	224(M)	224(M)	224(M)	224(M)	184(M)	134

7-2. X7R

		XYX.		11.11			
Dimension	Code	Rated Voltage					
Difficusion	Code	50V	100V	200V	250V	500V	630V
1210	1A	475	335	684	684	104	104
4949	1C	106	475	105	105	474	224
1812	2C	226(M)	106	225(M)	225(M)	105	474(M)
4005	1G	106	106	105	105	564	564
1825	2G	226(M)	226(M)	225(M)	225(M)	125(M)	125(M)
2220	1H	226	106	225	225	474	474
2220	2H	476(M)	226(M)	475(M)	475(M)	105	105
2225	11	106	106	275	275	564	564
2225	21	226(M)	226(M)	565	565	125(M)	125(M)

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(M) means M tolerance only.

7-3. Customizable, Please contact the liaison.

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8. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

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No.	Item		T	est Condition			Requirements		
1.	Visual and Dimensions					* No remarkable * Dimensions to o	defect. confirm to individual specification shee	et.	
2.	Capacitance	* Class I :				* Shall not exceed the limits given in the detailed spec.			
		* Class I : Cap.≤1000pF, 1.0±0.2Vrms, 1MHz±10%.				Dielectric	Cap. Range	Q/D.F.	
	Q/D.F.			0.2Vrms, 1KHz:		Dielectric		Q≥1000	
				,		Class I (C0G)	Cap.≥30pF		
3.	(Dissipation Factor)	* Class II :					Cap.<30pF	Q≥400+20C	
	i actor)			2Vrms, 1KHz±1		Class II (X7R)	1210≥3.3μF & 1812~2220≥10μF	D.F.≤5.0%	
		Cap.>10µF,	0.5±0.2	2Vrms, 120Hz±	20%.		Other	D.F.≤2.5%	
		* With no ele	ctrical lo	oad.					
	Temperature	T.C.	04.104.10	Operating T	Гетр.	T.C.	Capacitance Chang	ge	
4.	Coefficient	COG		-55~125°C a		C0G	Within ±30ppm/°C	;	
		X7R		-55~125°C a		X7R	Within ±15%		
		7			好有	信息			
		Rated Vol.	(V) A	Apply Voltage	Test Time	X			
	Insulation	≤100		1 times of U _R	Max. 120 sec.	Dielectric	Requirements		
5.	Resistance	100 <v≤50< td=""><td></td><td>1 times of U_R</td><td>60 sec.</td><td>Class I</td><td>≥10GΩ or RxC≥500Ω-F, whiche</td><td>ever is smaller</td></v≤50<>		1 times of U _R	60 sec.	Class I	≥10GΩ or RxC≥500Ω-F, whiche	ever is smaller	
		>500	30	500Vdc	60 sec.	Class II	≥10GΩ or RxC≥100Ω-F, whiche	ever is smaller	
		- 000		000140	3	A Sell			
		Rated V	'oltage	C	ondition	A	9		
		≤100 2.5 times of U _R 100 <v≤250 2.0="" of="" times="" u<sub="">R 250<v≤500 1.5="" of="" times="" u<sub="">R =630 1.2 times of U_R</v≤500></v≤250>				* No evidence of damage or flash over during test.			
6.	Dielectric								
	Strength								
		* Duration : 1 to 5 sec.			ZP/ZV	CC ITO ALL			
				rge current less	than 50mA.	500,1210			
					1201111				
			-	cles according	to the				
		temperature							
		Step		Temp.(°C)	Time(min.)	* No remarkable	damage.		
			-	ating temp. +0/-		* Cap. change :			
	Tomporoturo		oom tem		2~3	C0G Within ±2.5	5% or ±0.25pF, whichever is larger.		
7.	Temperature Cycle			ating temp. +3/-		* Q/D.F. :	J /U.		
	,		oom tem		2~3		of initial requirement.		
		* Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at				X7R : D.F.≤150% of initial requirement.			
		room temp.		or the their set	101 2412 1113 at	* I.R. : To meet the initial requirement.			
		* Measureme	ent to be	made after kee	eping at room temp.				
		for 24±2 hrs (Class I) or 48±4 hrs (Class II).							
		* Test temp. :	40±2°C) .		* No remarkable damage. * Cap. change : C0G Within ±5.0% or ±0.5pF, whichever is larger.			
		* Humidity : 9							
	Humidity	* Test time : {			II only) . To seed				
8.	(Damp Heat)				II only): To apply for 24±2 hrs at	X7R Within ±12 * Q/D.F. :	.J70.		
	Steady State	room temp.		io. IIII dioni set	10. 27±2 1113 at	C0G : Q≥350.			
		•		made after kee	eping at room temp.		% of initial requirement.		
		for 24±2 hrs	s (Class	I) or 48±4 hrs ((Class II).	* I.R. : ≥1GΩ or RxC≥50Ω-F, whichever is smaller.			
		, , ,							

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8. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No	Item	Test Condition	Requirements
9.	Humidity (Damp Heat) Load	* Test temp.: 40±2°C. * Humidity: 90~95%RH. * Test time: 500 +24/-0hrs. * To apply voltage: Rated voltage (500V max.). * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs (Class I) or 48±4 hrs (Class II).	* No remarkable damage. * Cap. change : C0G Within ±7.5% or ±0.75pF, whichever is larger. X7R Within ±12.5%. * Q/D.F. : C0G : Q≥200. X7R : D.F.≤200% of initial requirement. * I.R. : ≥500MΩ or RxC≥25Ω-F, whichever is smaller.
10.	High Temperature Load (Endurance)	* Test temp. : 125±3°C. * To apply voltage : Dielectric Rated Vol.(V) Apply Voltage ≤100 2.0 times of U _R C0G/X7R 200≤V≤ 500 1.5 times of U _R =630 1.2 times of U _R * Exception items (X7R only) (1) 150% of rated voltage for below range : Rated Vol.(V) Size Cap. Range ALL ALL Cap.≥106 1210 1812 50V & 100V 1825 Cap.≥105 2220 2225 (2) 120% of rated voltage for below range : Size Dielectric Rated Voltage Capacitance 2220 X7R ≥100V Cap.≥15µF (3) 100% of rated voltage for below range : Size Dielectric Rated Voltage Capacitance 1210 X7R ≥100V Cap.≥3.3µF * Test time : 1000 +24/-0 hrs. * Before initial measurement (Class II only) : To app de-aging at 150°C for 1hr then set for 24±2 hrs room temp. * Measurement to be made after keeping at room temp for 24±2 hrs (Class II) or 48±4 hrs (Class II).	* No remarkable damage. * Cap. change: C0G Within±3.0% or ±0.3pF, whichever is larger. X7R Within±12.5%. * Q/D.F.: C0G: Q≥350. X7R: D.F.≤200% of initial requirement. * I.R.: ≥1GΩ or RxC≥50Ω-F, whichever is smaller.

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8. RELIABILITY TEST CONDITIONS AND REQUIREMENTS

No.	Item	Test Condition	Requirements
11.	Adhesive Strength of Termination	* Capacitors mounted on a substrate. A force of 10N applied perpendicular to the place of substrate and parallel the line joining the center of terminations for 10±1 second. Pressurizing force Capacitor P.C. Board	* No remarkable damage or removal of the terminations.
14.	Bending Test	* The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1mm per second until the deflection becomes 5mm. R = 230 Unit : mm	This capacitance change means the change of capacitance under specified flexure of substrate from the capacitance measured before the test)
15.	Vibration Resistance	* Vibration frequency: 10~55 Hz/min. * Total amplitude: 1.5mm. * Test time: 6 hrs. (Two hrs each in three mutually perpendicular directions) * Before initial measurement (Class II only): To apply de-aging at 150°C for 1hr then set for 24±2 hrs at room temp. * Measurement to be made after keeping at room temp. for 24±2 hrs (Class II) or 48±4 hrs (Class II).	* No remarkable damage. * Cap. change and D.F. : To meet initial spec.

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9. APPLICATION NOTES

STORAGE

To prevent the damage of solderability of terminations, the following storage conditions are recommended: Indoors under 5 ~ 40°C and 20% ~ 70% RH.

No harmful gases containing sulfuric acid, ammonia, hydrogen sulfide or chlorine.

Packaging should not be opened until the capacitors are required for use. If opened, the pack should be re-sealed as soon as is practicable. Taped product should be stored out of direct sunlight, which might promote deterioration in tape or adhesion performance. The product is recommended to be used within 12 months after shipment and checked the solderability before use.

HANDLING

Chip capacitors are dense, hard, brittle, and abrasive materials. They are liable to suffer mechanical damage, in the form of cracks or chips. Chip Capacitors should be handled with care to avoid contamination or damage. To use vacuum or plastic tweezers to pick up or plastic tweezers is recommended for manual placement. Tape and reeled packages are suitable for automatic pick and placement machine.

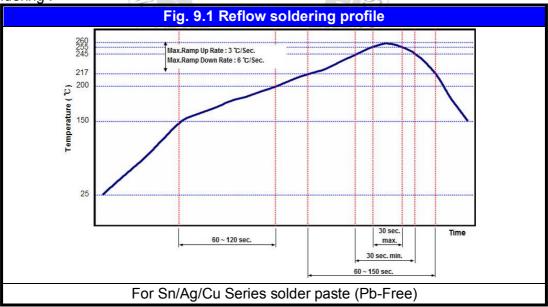
PREHEAT

In order to minimize the risk of thermal shock during soldering, a carefully controlled preheat is required. The rate of preheat should not exceed 3°C per second.

SOLDERING

Use middy activated rosin RA and RMA fluxes do not use activated flux. The amount of solder in each solder joint should be controlled to prevent the damage of chip capacitors caused by the stress between solder, chips, and substrate.

a.) Reflow soldering:



COOLING

After soldering, cool the chips and the substrate gradually to room temperature. Natural cooling in air is recommended to minimize stress in the solder joint.

CLEANING

All flux residues must be removed by using suitable electronic-grade vapor-cleaning solvents to eliminate contamination that could cause electrolytic surface corrosion. Good results can be obtained by using ultrasonic cleaning of the solvent. The choice of the proper system is depends upon many factors such as component mix. flux, and solder paste and assembly method. The ability of the cleaning system to remove flux residues and contamination from under the chips is very important.

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